FEATURES:

Performance to 18 GHz.

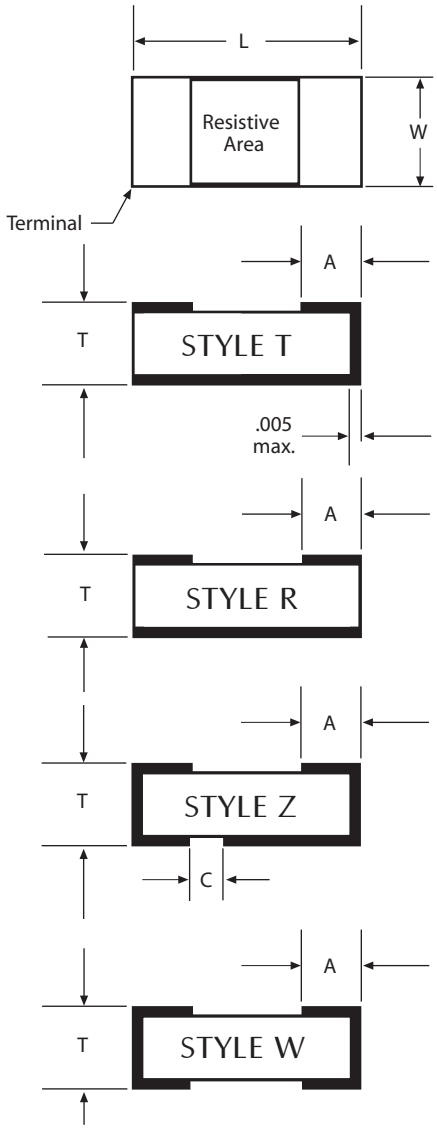
Highly reliable multilayer electrode construction.

Compatible with both flow soldering and reflow soldering.

Highly stable in auto placement surface mounting applications.

Reliability programs designed to customer requirements.

Proven designs for Microwave applications.



GENERAL SPECIFICATIONS:

STANDARD RESISTANCE RANGE: 5 ohms to 5,000 ohms.
Other values available.
TOLERANCE: ±1%, ±2%, ±5% and ±10%.
TEMPERATURE COEFFICIENT: ±100 PPM/°C. (-55°C to +125°C with 25°C as reference). Other temperature coefficients available.
RESISTIVE ELEMENTS: Proprietary film.
SOLDERABLE TERMINALS: Electroplated Tin over Nickel.
SUBSTRATE: Beryllium Oxide.
TERMINAL STYLE:

T - Termination, one sided wraparound.
R - Resistor, Metallized backing.
W - Resistors, two sided wraparound.

HIGH POWER BERYLLIUM OXIDE SUBSTRATE (BeO)

RPC TYPE ±.005	W (inches) ±.005	L (inches) ±.005	T (inches) ±.008	A (inches)	(°C/Watt)	MAXIMUM POWER
RPC50-50	.050	.050	.010	.012	1.46	5 watts
RPC50-100	.050	.100	.010	.017	1.57	10 watts
RPC75-150	.075	.150	.010	.020	1.18	15 watts

1. Thermal resistance in °C/W between film and mounting surface.
2. Maximum film temperature is 150°C.
3. Power ratings are based upon 100°C heat sink temperature.
4. "T" is substrate thickness, add 0.005 for terminal and film thickness.